6. The capacitive sensing device as described in claim 1, wherein each of said first set of patterned conductive traces has a width less than approximately 12 micrometers.

7. The capacitive sensing device as described in claim 1, wherein each of said first set of patterned conductive traces has a width such that each of said first set of patterned conductive traces is not required to be formed of a substantially transparent material.

8. The capacitive sensing device as described in claim 1, wherein each of said first set of patterned conductive traces has a width less than a width of a pixel of said underlying image.

9. The capacitive sensing device as described in claim 1, wherein each of said first set of patterned conductive traces is a capacitive sensing element.

10. The capacitive sensing device as described in claim 1, wherein said substantially transparent substrate is a component of said information display device.

11. The capacitive sensing device as described in claim 1, wherein said substantially transparent substrate is selected from a group consisting of:

a glass, a plastic, and a crystalline material.

12. The capacitive sensing device as described in claim 1, wherein said first set of patterned conductive traces is formed of at least one layer of material that is substantially opaque.

13. The capacitive sensing device as described in claim 1, wherein said first set of patterned conductive traces is formed of at least one layer of material that is substantially non-reflective.

14. The capacitive sensing device as described in claim 1, further comprising:

a landing pad region formed above said substantially transparent substrate for coupling a sensing circuit component to said substantially transparent substrate.

15. A method for fabricating a capacitive sensing device, said method comprising:

utilizing a substantially transparent substrate; and

patterning a first set of conductive traces above said substantially transparent substrate, each of said first set of conductive traces having a width such that said capacitive sensing device does not have to be arranged with respect to an underlying image in order to avoid deleterious obstruction of said underlying image by said first set of conductive traces, said underlying image is separate from said capacitive sensing device, wherein said capacitive sensing device is fabricated separately from active components of an information display.

16. The method as described in claim 15, wherein said patterning said first set of conductive traces comprises a process selected from the group consisting of:

a lithographic process, a printing process, electron beam lithography, screen printing, inkjet printing, offset printing, electroplating, stamping, and LIGA.

17. The method as described in claim 15, further comprising:

patterning a second set of conductive traces above and coupled to said substantially transparent substrate.

18. The method as described in claim 17, wherein each of said second set of conductive traces has a width such that said capacitive sensing device does not have to be arranged with respect to said underlying image in order to avoid deleterious obstruction of said underlying image by said second set of conductive traces.

19. The method as described in claim 17, wherein said patterning said second set of conductive traces comprises a process selected from the group consisting of:

a lithographic process, a printing process, electron beam lithography, screen printing, inkjet printing, offset printing, electroplating, stamping, and LIGA.

20. The method as described in claim 17, wherein said first set of conductive traces and said second set of conductive traces are substantially orthogonal to each other.

21. The method as described in claim 17, wherein said first set of conductive traces or said second set of conductive traces comprises at least one layer of substantially opaque material.

22. The method as described in claim 17, further comprising:

depositing an insulating material above at least a portion of said first set of conductive traces.

23. The method as described in claim 17, wherein said insulating material is substantially transparent.

24. The method as described in claim 17, wherein said first set of conductive traces or said second set of conductive traces is formed of at least one layer of material that is substantially non-reflective.

25. The method as described in claim 17, wherein said patterning said second set of conductive traces comprises:

patterning a landing pad region above said substantially transparent substrate for coupling a sensing circuit component to said substantially transparent substrate.

26. The method as described in claim 15, wherein said substantially transparent substrate is a component of said information display device.

27. The method as described in claim 15, wherein said substantially transparent substrate is selected from a group consisting of:

a glass, a plastic, and a crystalline material.

28. The method as described in claim 15, wherein said first set of conductive traces is formed of at least one layer of material that is substantially opaque.

29. The method as described in claim 15, wherein said patterning said first set of conductive traces comprises:

patterning a landing pad region above said substantially transparent substrate for coupling a sensing circuit component to said substantially transparent substrate.

30. The method as described in claim 15, wherein each of said first set of conductive traces has a width less than approximately 12 micrometers.

31. The method as described in claim 15, wherein each of said first set of conductive traces has a width such that each of said first set of conductive traces is not required to be formed of a substantially transparent material.

32. The method as described in claim 15, wherein each of said first set of conductive traces has a width less than a pixel width of said underlying image.

33. The method as described in claim 15, wherein each of said first set of conductive traces is a capacitive sensing element.